

SURFACE MOUNT SCHOTTKY RECTIFIER

REVERSE VOLTAGE: 30 V
CURRENT: 0.5 A

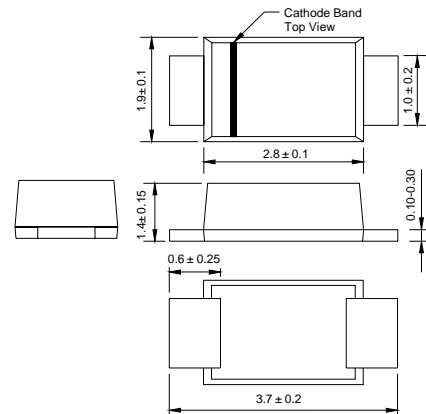
FEATURES

- Low profile package
- For surface mouted applications
- Idear for automated placement
- Low power loss,high efficiency
- High temperature soldering:
250 /10 seconds at terminals

MECHANICAL DATA

- Case:JEDEC SOD-123FL,molded plastic over passivated chip
- Terminals:Solder Plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Weight: 0.003 ounces, 0.01 gram
- Device marking code:B3

SOD-123FL



Dimensions in millimeters

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 ambient temperature unless otherwise specified.

Single hase,half wave,60Hz,resistive or inductive load.For capactive load,derate current by 20%.

ABSOLUTE RATINGS

Parameter	Symbol	Value	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	30	V
Maximum working peak reverse voltage	V_{RWM}	30	V
Maximum DC blocking voltage	V_R	30	V
Maximum average forward rectified current at rated V_R @ $T_L=100$	$I_{(AV)}$	0.5	A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load	I_{FSM}	5.5	A
Maximum instantaneous forward voltage @ $I_F=0.1A, T_J=25$ $I_F=0.5A, T_J=25$	V_F	0.375 0.43	V
Maximum DC reverse current @ Rated dc Voltage, $T_C=25$ at rated DC blocking voltage $V_R=15V, T_C=25$	I_R	130 20	μA
Typical thermal resistance junction to ambient (NOTE 1)	$R_{j\theta A}$	206	/W
Typical thermal resistance junction to lead	$R_{j\theta L}$	150	/W
Operating temperature range	T_J	-55----+150	
Storage temperature range	T_{STG}	-55----+150	

NOTES:1.inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

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FIG. 1 - TYPICAL FORWARD CURRENT DERATING CURVE

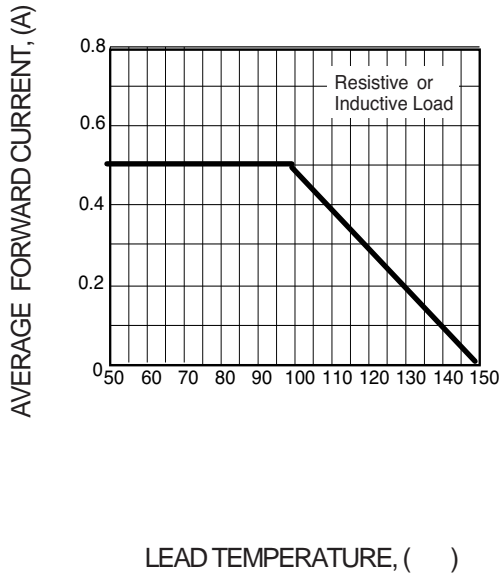


FIG. 2 - MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

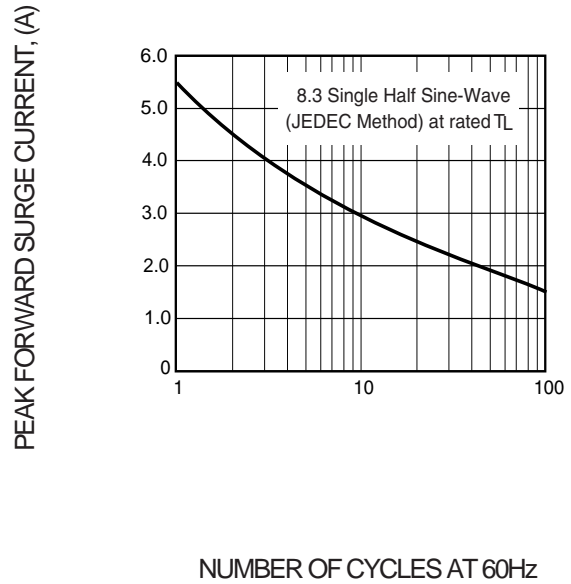


FIG. 3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

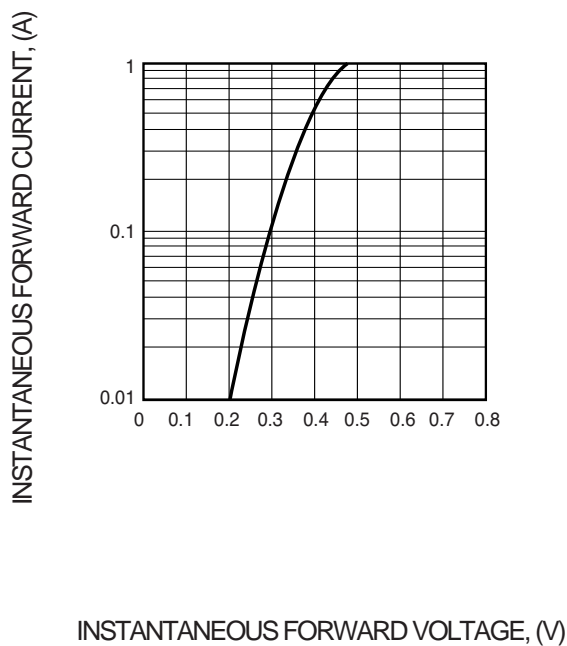


FIG. 4 - TYPICAL REVERSE CHARACTERISTICS

